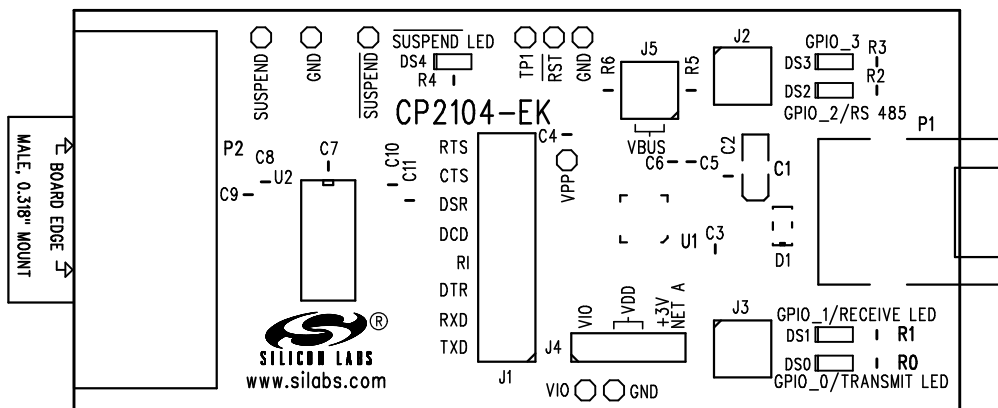
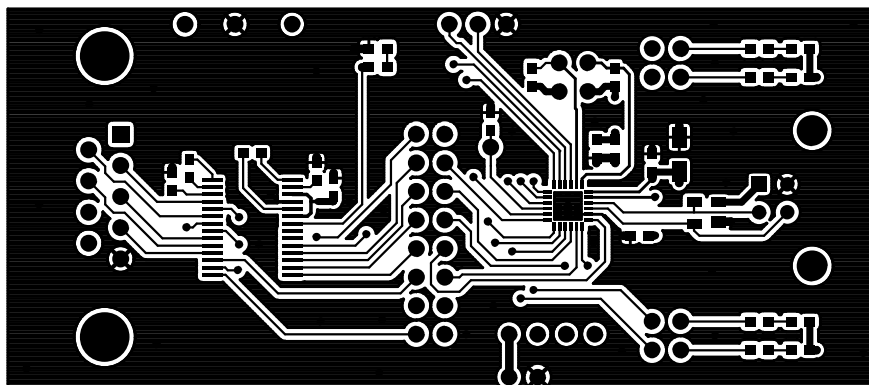
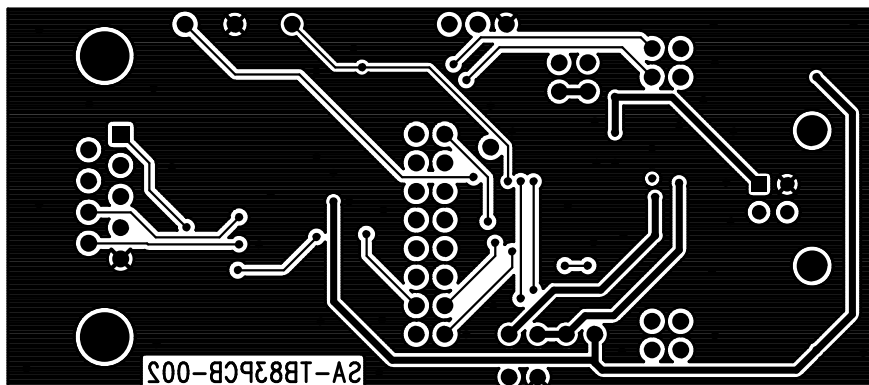




SILKSCREEN TOP
SILICON LABS SA-TB83PCB-002 (CP2104-EK)



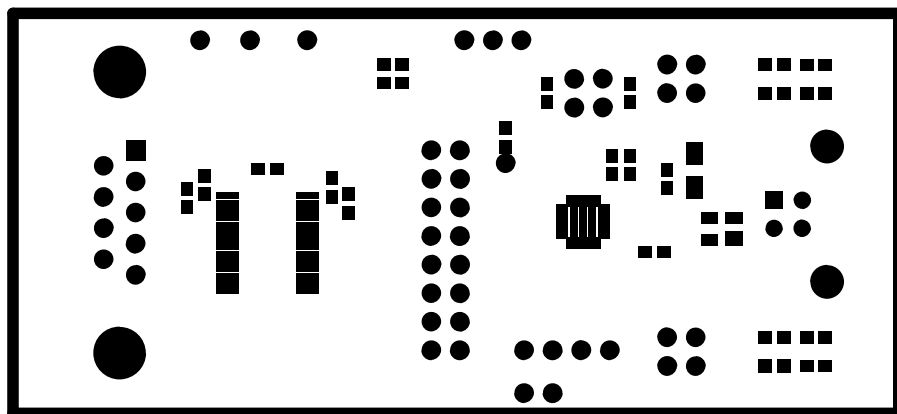
SILICON LABS SA-TB83PCB-002 (CP2104-EK)^{TOP}



SILICON LABS SA-TB83PCB-002 (CP2104-EK) ^{BOTTOM}

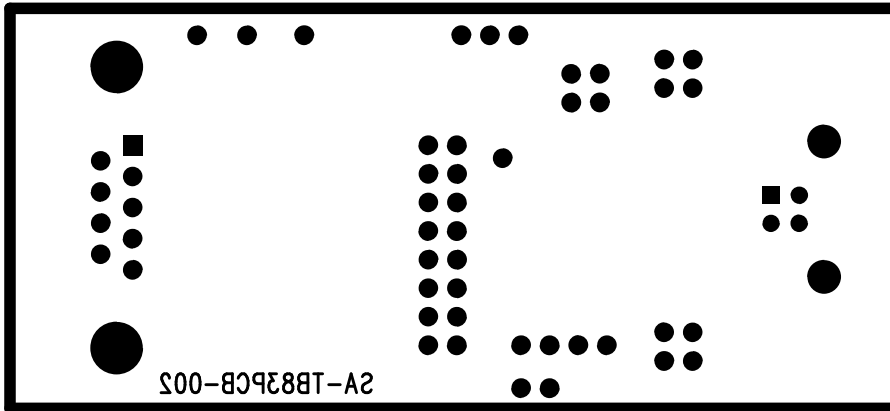


SILKSCREEN BOT
SILICON LABS SA-TB83PCB-002 (CP2104-EK)



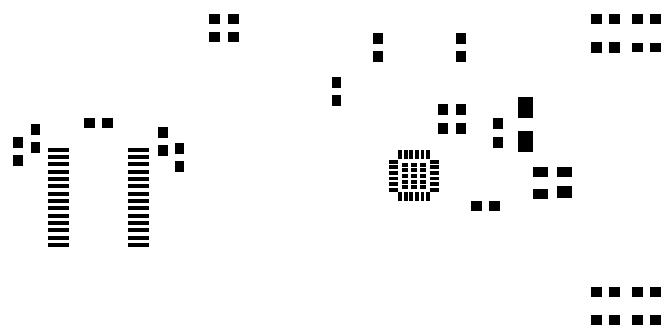
SILICON LABS SA-TB83PCB-002 (CP2104-EK)

SOLDERMASK TOP



SILICON LABS SA-TB83PCB-002 (CP2104-EK)

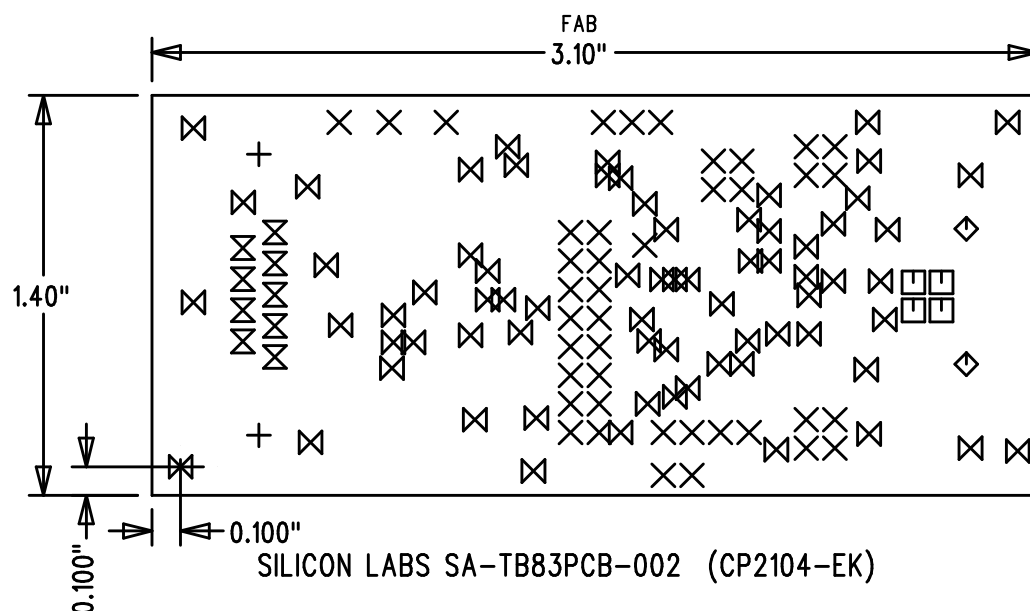
SOLDERMASK BOT



SILICON LABS SA-TB83PCB-002 (CP2104-EK)

PASTEMASK TOP

SIZE	QTY	SYM	PLTD
125	2	+	PLTD
40	41	X	PLTD
35	4	□	PLTD
93	2	◇	PLTD
46	9	⊗	PLTD
15	71	⊗	PLTD



NOTES : UNLESS OTHERWISE SPECIFIED

1. MANUFACTURE IN ACCORDANCE WITH IPC-6012, TYPE 3, CLASS 2.
2. END PRODUCT FEATURES SHALL NOT VARY MORE THAN 20% FROM ARTWORK ORIGINALS.
3. LAMINATE AND PREPREG SHALL BE AS PER IPC-4101/26,83,98 WITH A DECOMPOSITION TEMPERATURE $\geq 345^{\circ}\text{C}$, COLOR, NATURAL.
4. COPPER WEIGHT SHALL BE 1.0 OZ./SQ. FT. BEFORE PLATING.
5. ALL PLATED THROUGH HOLES SHALL HAVE A MINIMUM OF 0.001" COPPER.
6. DRILL HOLE TOLERANCE AFTER PLATING SHALL BE ± 0.003 ".
7. MINIMUM ANNULAR RING SHALL BE 0.001".
8. MINIMUM ANNULAR RING AT EMERGENT CONDUCTORS SHALL BE 0.003".
9. FINAL PCB THICKNESS SHALL BE 0.062" ± 0.006 " ACROSS PADS.
10. WARP/TWIST SHALL NOT EXCEED 0.010 INCH PER INCH.
11. FINISH SHALL BE LPI, BLUE S.M.O.B.C., BOTH SIDES, PLATE WITH 0.8 μm MIN. THICKNESS HARD GOLD OVER 2.5 μm MIN. LOW STRESS NICKEL, BALANCE RoHS COMPLIANT ENIG.
12. SILKSCREEN WITH NONCONDUCTIVE WHITE EPOXY INK.
13. NO VENDOR MARKINGS OR ALTERATIONS SHALL BE PERMITTED ON ANY METAL OR SILKSCREEN LAYERS.

LAYER STACKUP

FILE NAMES

SILKSCREEN TOP	TOPSILK.TSK
SOLDERMASK TOP	SMASKTOP.SMT
TOP	TOP.TOP
BOTTOM	BOTTOM.BOT
SOLDERMASK BOTTOM	SMASKBOT.SMB
SILKSCREEN BOTTOM	BOTSILK.BSK

SCALE: NONE

